

# 3A, 100V - 200V Ultra Fast Surface Mount Rectifier

#### **FEATURES**

- Planar technology
- Low power loss, high efficiency
- Ideal for automated placement
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- High frequency switching
- DC/DC
- Snubber

## **MECHANICAL DATA**

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.028g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	3	Α	
$V_{RRM}$	100 - 200	V	
I <sub>FSM</sub>	85	Α	
T <sub>J MAX</sub>	175	°C	
Package	SOD-128		
Configuration	Single die		









**SOD-128** 



PARAMETER		SYMBOL	PU3BFS	PU3DFS	UNIT
Marking code on the device			PU3BFS	PU3DFS	
Repetitive peak reverse voltage		$V_{RRM}$	100	200	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	70	140	V
Forward current		I <sub>F</sub>	3		Α
Surge peak forward current single half	t = 8.3ms		85 170		A
sine-wave superimposed on rated load	t = 1.0ms	- I <sub>FSM</sub>			
Junction temperature		TJ	-55 to +175		°C
Storage temperature		T <sub>STG</sub>	-55 to +175		°C

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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\Theta JL}$	14	°C/W
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	74	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	19	°C/W

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 25°C		0.81	-	V
	I <sub>F</sub> = 3.0A, T <sub>J</sub> = 25°C	.,	0.86	0.93	V
	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 125°C	V <sub>F</sub>	0.66	-	V
	I <sub>F</sub> = 3.0A, T <sub>J</sub> = 125°C		0.73	-	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C		-	2	μA
	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	10	μA
Junction capacitance	1MHz, V <sub>R</sub> = 4.0V	CJ	47	-	pF
Daviere resource times	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	4	-	25	ns
Reverse recovery time	$I_F = 1.0A$ , di/dt = 50A/ $\mu$ s, $V_R = 30V$	t <sub>rr</sub>	31	-	
Reverse recovery current		I <sub>RM</sub>	4.9	-	Α
Reverse recovery charge	$I_F = 3.0A$ , di/dt = 200A/ $\mu$ s, $V_R = 100V$	Q <sub>rr</sub>	51	-	nC
Reverse recovery time		t <sub>rr</sub>	23	-	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION		
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING
PU3xFS	SOD-128	14,000/ Tape & Reel

## Notes:

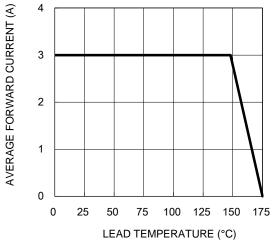
1. "x" defines voltage from 100V(PU3BFS) to 200V(PU3DFS)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve



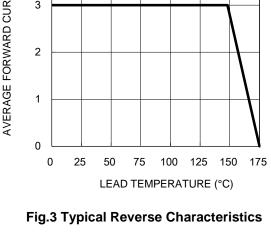


Fig.2 Typical Junction Capacitance

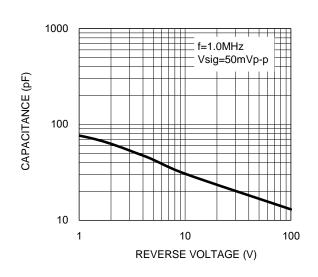
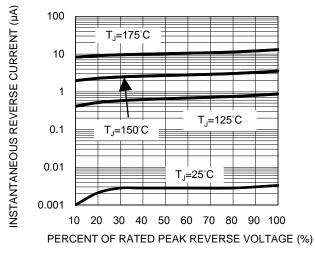


Fig.4 Typical Forward Characteristics



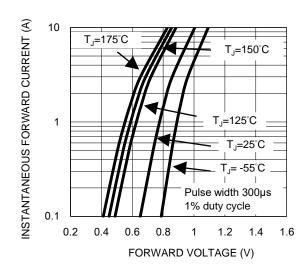
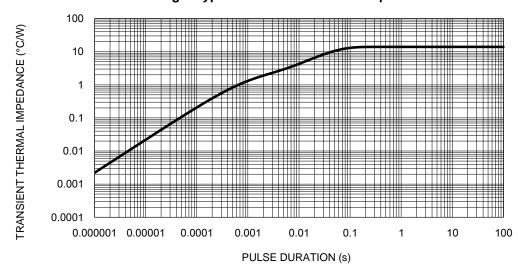


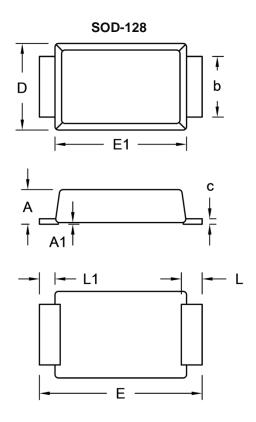
Fig.5 Typical Transient Thermal Impedance





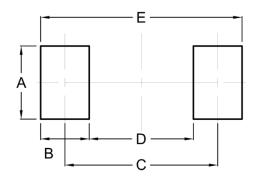


# **PACKAGE OUTLINE DIMENSIONS**



DIM.	Unit (mm)		Unit	(inch)
Dilvi.	Min.	Max.	Min.	Max.
Α	0.90	1.10	0.035	0.043
A1	0.00	0.10	0.000	0.004
b	1.60	1.90	0.063	0.075
С	0.10	0.22	0.004	0.009
D	2.30	2.70	0.091	0.106
E	4.40	5.00	0.173	0.197
E1	3.60	4.00	0.142	0.157
L	0.40	0.80	0.016	0.031
L1	0.30	0.60	0.012	0.024

# **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

# **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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